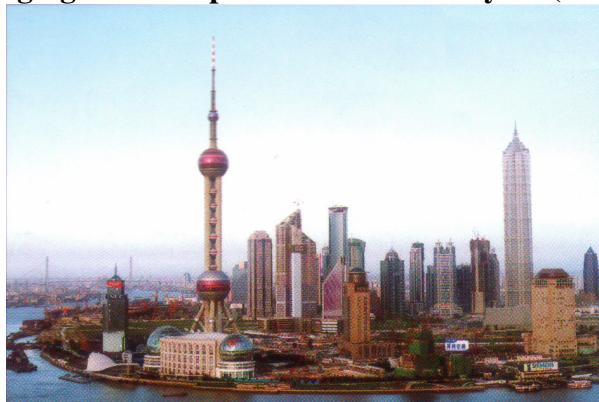




Announcement and Call for Papers
The 7th IEEE CPMT International Conference on High Density Microsystem Design and Packaging and Component Failure Analysis (HDP'05)



Date: June 27 – 30, 2005

Venue: Shanghai University, Bao Shan Campus, Shanghai, China

Co-sponsored by

Shanghai Science and Technology Commission, Shanghai Government

IEEE CPMT Society

IEEE CPMT Scandinavian Chapter

IEEE CPMT China Chapter

Microsystem design, manufacturing, assembly and packaging technology is playing a key technology for the progress of the microsystems and microelectronics industry in the world. China is not an exception. Therefore, many multi-national companies are establishing new facilities in China for expanding their global business and interest. Following the successful previous conferences, we are proud to announce the 7th International IEEE CPMT Symposium on High Density Microsystem Design and Packaging and Component Failure Analysis in Electronics Manufacturing (HDP'05).

Scope for the Symposium: The Symposium will cover the following areas and subjects:

- High density design and packaging including micro- and nanosystems, microelectronics and opto-electronics design and packaging, SOP, SIP, CSP, BGA, Flip-chip, Chip on Board, Surface Mount Technology and other novel emerging technology
- High density substrate including integrated passives and active devices
- MEMS and MOEMS design, packaging and assembly
- Microsystems manufacturing issues including cleaning issues, quality control, logistics, repair, process optimization, statistic process controls, ISO compliance, tooling or equipment, early manufacturing involvement initiatives and yield and test innovations used to enhance manufacturing processes or products related to high density substrates, single chip and multichip packaging, chip bumping and integrated component technologies
- Component failure analysis techniques including non-destructive X-ray, ultrasonic microscopy, IR-microscopy etc
- Simulation and modelling for packaging and microsystems and microelectronics



manufacturing processes

- Thermal management
- Environmental design and materials development including life cycle analysis and end of life strategy etc
- Cost reengineering, improvements and analysis for electronics packaging processes and products

Documentation: The documentation from the conference will be published as an IEEE Conference proceedings with CD ROM with full length papers as well as in book form in English.

Journal publication: In addition, high quality papers will be selected for consideration to be published as special editions of the IEEE CPMT Transactions.

Language: English will be used.

You are welcome to submit an abstract with max 300 words that cover the topic, experimental approach, results and conclusions for the paper by February 28, 2005 Notification of abstracts will be made by March 15, 2005, Final paper is requested by April 30, 2005.

We are also interested to have exhibitors from materials, equipment suppliers to exhibit their products.

For further information please contact Liqiang Cao at smit@mail.shu.edu.cn. or johan.liu@mc2.chalmers.se at SMIT Centre, Shanghai, China and Sweden.

Further information will be posted at the website at www.smit-shu.com

Symposium Chair: Minglun Fang, Shanghai University, China

Symposium co-chair: Johan Liu, SMIT Centre, Shanghai University, China and Chalmers University of Technology, Sweden

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Contact Information Form

I am interested to join the HDP'05. I would like to receive further information on the Conference _____ (Please mark here).

We are interested to make an exhibition _____ (Please mark here).

Registration information:

Name: _____ Title: _____

Organisation: _____

Address: _____ P O Box: _____

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I would like to submit a paper. The title of the paper is:

We are all looking forward to seeing you all in 2005 here at SMIT Center, Shanghai University, China

Hotel Information: Most quality hotels such as Sheraton, SAS Radiosson Hotel, Holiday Inn, Regents etc. at reasonable rates ranging from RMB from 500 to 700 per night (70-100 USD). Please make your reservations directly with the hotel via Internet or other means. Alternatively, SMIT Center, Shanghai University can offer good hotel-like guest rooms within campus at RMB200 per night. If you are interested in this accommodation, please contact Liqiang Cao for details:

Liqiang Cao, SMIT Center, Shanghai University, China



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